

M66313FP 32-Bit LED Driver with Shift Register and Latch

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Description

The M66313FP is a semiconductor integrated circuit for LED array driver with 32-bit serial-input, parallel-output shift register, equipped with direct set input and output latches.

The M66313FP guarantees sufficient 24 mA output current to drive anode common LED, allowing 32-bit simultaneous and continuous current output.

The parallel outputs are open-drain outputs.

The M66313FP employs CMOS technology, allowing considerable reduction of power dissipation, compared to previous BIPOLAR or Bi-CMOS products.

In addition, the pin configuration is suitable for easy wiring on the printed circuit board.

Features

- High output current.
- All parallel output I_{OL} = +24 mA, LEDs can be turned on simultaneously.
- Low power dissipation : 200 μW/package (max) (V_{CC} = 5 V, Ta = 25°C, quiescent state)
- High noise margin
- Employment of Schmitt-trigger circuit on all inputs allows application with long wiring.
- Direct set input (\overline{S}_D)
- Open-drain output ($\overline{\mathbf{Q}}_1$ to $\overline{\mathbf{Q}}_{32}$)
- Serial data output for cascading (SQ₃₂)
- Wide operating temperature range (Ta = -40 to $+85^{\circ}$ C)
- Pin configuration for easy layout on PCB.
 - (Pin configuration allows easy cascade connection or LED connection)

Application

LED array drive for eraser unit of a copying machine

LED array drive of a button telephone set

Various LED modules

Block Diagram



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Pin Arrangement



Functional Description

The employment of silicon gate CMOS process of the M66313FP guarantees low power dissipation and maintains high noise margin as well as high output current and high speed required to drive LEDs.

Each shift register bit consists of a flip-flop for shifting and an output latch.

The shift operation takes place when the clock input CK changes from low-level to high-level.

The serial data input A corresponds to the data input of the first-stage shift register, and the shift register is shifted in sequence when a pulse is applied to CK.

The parallel outputs \overline{Q}_1 to \overline{Q}_{32} are open-drain outputs.

If the latch-enable input $\overline{\text{LE}}$ is turned high-level, the content of the shift register at that instant is latched.

To expand the number of bits, use the serial data output SQ₃₂ which shows the output of the shift register of the 32nd bit.

If the direct set input \overline{S}_D is turned low-level, shift register and latches are set.

If the high-level input is applied to the output enable input \overline{OE} , \overline{Q}_1 to \overline{Q}_{32} are set to the high-impedance state, but SQ₃₂ is not set to the high-impedance state. The shift operation is not affected when \overline{OE} is changed.

M66313FP

Function Table (Note)

Operation		I	npu	t		Parallel Data Output										Serial Data																						
Mode	\overline{S}_{D}	CK	ĪĒ	А	ŌĒ	\overline{Q}_1	$\overline{\mathtt{Q}}_2$	\overline{Q}_3	\overline{Q}_4	\overline{Q}_5	\overline{Q}_6	\overline{Q}_7	\overline{Q}_8	\overline{Q}_{9}	\overline{Q}_{10}	\overline{Q}_{11}	\overline{Q}_{12}	\overline{Q}_{13}	\overline{Q}_{14}	\overline{Q}_{15}	\overline{Q}_{16}	\overline{Q}_{17}	\overline{Q}_{18}	\overline{Q}_{19}	\overline{Q}_{20}	\overline{Q}_{21}	\overline{Q}_{22}	\overline{Q}_{23}	\overline{Q}_{24}	$\overline{\mathtt{Q}}_{25}$	\overline{Q}_{26}	$\overline{\mathtt{Q}}_{27}$	\overline{Q}_{28}	\overline{Q}_{29}	\overline{Q}_{30}	\overline{Q}_{31}	\overline{Q}_{32}	SQ ₃₂
Set	L	Х	Х	Х	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	н
Shift	Н	1	L	Н	L	L	\overline{Q}^{0}_{1}	\overline{Q}_{2}^{0}	\overline{Q}_{3}^{0}	\overline{Q}_{4}^{0}	$\overline{Q}{}^{0}_{5}$	$\overline{Q}{}^{0}_{6}$	\overline{Q}^{0}_{7}	$\overline{Q}{}^{0}_{8}$	$\overline{Q}{}^{0}{}_{9}$	Q ⁰ 10	Q011	Q012	Q013	Q014	Q015	Q ⁰ 16	Q ₁₇	Q ⁰ 18	Q ⁰ 19	Q ⁰ 20	Q ⁰ 21	Q ⁰ 22	Q ₂₃	Q ⁰ 24	$\overline{Q}{}^{0}_{25}$	$\overline{Q}{}^{0}_{26}$	Q ⁰ 27	Q ⁰ 28	Q ⁰ 29	$\overline{Q}{}^{0}{}_{30}$	$\overline{Q}{}^{0}{}_{31}$	q ⁰ ₃₁
	Н	Ŷ	L	L	L	Z	\overline{Q}^{0}_{1}	\overline{Q}_{2}^{0}	\overline{Q}^{0}_{3}	\overline{Q}_{4}^{0}	$\overline{Q}{}^{0}_{5}$	$\overline{Q}{}^{0}_{6}$	\overline{Q}^{0}_{7}	$\overline{Q}{}^{0}{}_{8}$	$\overline{Q}{}^{0}{}_{9}$	Q ₁₀	Q ⁰ 11	Q ⁰ 12	Q013	Q ⁰ 14	Q ⁰ 15	Q ⁰ 16	Q ⁰ 17	Q ⁰ 18	Q ⁰ 19	Q ⁰ 20	Q ⁰ 21	Q ⁰ 22	$\overline{Q}{}^{0}_{23}$	Q ⁰ 24	$\overline{Q}{}^{0}_{25}$	$\overline{Q}{}^{0}_{26}$	Q ⁰ 27	Q ⁰ 28	Q ⁰ 29	$\overline{Q}{}^{0}{}_{30}$	$\overline{Q}{}^{0}{}_{31}$	q ⁰ 31
Latch	Н	Х	Н	Х	L	$\overline{Q}{}^{0}{}_{1}$	\overline{Q}^{0}_{2}	$\overline{Q}{}^{0}{}_{3}$	\overline{Q}^{0}_{4}	$\overline{Q}{}^{0}{}_{5}$	$\overline{Q}{}^{0}_{6}$	$\overline{Q}{}^{0}{}_{7}$	$\overline{Q}{}^0{}_8$	$\overline{Q}{}^{0}{}_{9}$	\overline{Q}^{0}_{10}	$\overline{Q}{}^{0}_{11}$	\overline{Q}^{0}_{12}	\overline{Q}^{0}_{13}	Q ⁰ 14	Q ⁰ 15	\overline{Q}^{0}_{16}	Q ⁰ 17	Q ⁰ 18	Q ⁰ 19	\overline{Q}^{0}_{20}	\overline{Q}^{0}_{21}	\overline{Q}^{0}_{22}	\overline{Q}^{0}_{23}	$\overline{Q}{}^{0}_{24}$	$\overline{Q}{}^{0}_{25}$	$\overline{Q}{}^{0}_{26}$	$\overline{Q}{}^{0}_{27}$	$\overline{Q}{}^{0}_{28}$	\overline{Q}^{0}_{29}	\overline{Q}^{0}_{30}	$\overline{Q}{}^{0}{}_{31}$	$\overline{Q}{}^{0}{}_{32}$	q ₃₂
Output disable	X	Х	Х	Х	Н	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Z	Ζ	Ζ	Ζ	Z	Z	Ζ	Ζ	Ζ	Ζ	Z	Z	Z	Ζ	Ζ	q ₃₂

Note 1: Transition from low-to-high-level.

 $\overline{Q}{}^0\!\!:$ Shows the status of output \overline{Q} before CK input changes.

X: Irrelevant

q⁰: The content of shift register before CK changes.

q: The content of the shift register.

Z: High-impedance state.

Absolute Maximum Ratings



 $(Ta = -40 \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted})$

ltem		Symbol	Ratings	Unit	Conditions
Supply voltage		V _{CC}	-0.5 to + 7.0	V	
Input voltage		VI	–0.5 to V _{CC} + 0.5	V V	
Output voltage	utput voltage			V	
Input protection diode current	I _{IK}	-20	mA	$V_{I} < 0 V$	
			20		$V_{I} > V_{CC}$
Output parasitic diode current	I _{ок}	-20	mA	$V_O < 0 V$	
			20		$V_{O} > V_{CC}$
Output current	\overline{Q}_1 to \overline{Q}_{32}	lo	50	mA	
	SQ ₃₂		±25		
Supply/GND current		Icc	-920, +20	mA	V _{CC} , GND
Power dissipation		Pd	650	mW	
Storage temperature range		Tstg	-65 to +150	°C	

Recommended Operating Conditions

			Limits					
Item	Symbol	Min	Тур	Max	Unit			
Supply voltage	V _{CC}	4.5	5	5.5	V			
Input voltage	VI	0	—	V _{CC}	V			
Output voltage	Vo	0	—	V _{CC}	V			
Operating free-air ambient temperature	Topr	-40	—	+85	°C			
range								

Electrical Characteristics

$(V_{CC} = 4.5 \text{ to } 5.5)$	V, u	nless oth	erwise	noted)
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	Limits										
			٦	「a = 25°0	C	Ta = -40	to +85°C				
ltem		Sym bol	Min	n Typ ^(Note1) Max		Min	Max	Unit	Conditions		
Positive-going threshold volta	ng V_{T+} 0.35× V_{CC} 2. Ditage		2.8	$0.7 \times V_{CC}$	$0.35 \times V_{CC}$	$0.7 \times V_{CC}$	V	$V_0 = 0.1V, V_0$ $ I_0 = 20\mu A$	_{CC} -0.1V		
Negative-goin threshold volta	g age	V _{T-}	$0.2 \times V_{CC}$	2	$0.55 \times V_{CC}$	$0.2 \times V_{CC}$	$0.55 \times V_{CC}$	V	$V_{O} = 0.1V, V_{O}$ $ I_{O} = 20\mu A$	/ _{cc} –0.1V 4	
High-level output	SQ ₃₂	V _{он}	V _{CC} -0.1	—	_	V _{CC} -0.1	_	V	$\label{eq:VI} \begin{split} V_I &= V_{T+}, V_{T-} \\ V_{CC} &= 4.5 V \end{split}$	I _{OH} = –20μΑ	
voltage			3.83	—	_	3.66	_			$I_{\text{OH}} = -4mA$	
Low-level	\overline{Q}_1 to	V _{OL}		—	0.1		0.1	V	$V_I = V_{T\scriptscriptstyle +}, V_{T\scriptscriptstyle -}$	$I_{OL}=20\mu A$	
output	\overline{Q}_{32}			0.20	0.41		0.50		$V_{CC} = 4.5V$	$I_{OL}=24mA$	
voltage			_	0.25	0.48		0.55 (Note 2)		G	$I_{OL} = 28 m A$	
	SQ ₃₂		-	_	0.1	-	0.1			$I_{OL}=20\mu A$	
			-	_	0.44	-	0.53	\mathbf{O}		$I_{\text{OL}}=4mA$	
High-level inpu current	ut	I _{IH}		_	0.5		5.0	μA	$V_I = V_{CC}, V_{CC}$	= 5.5V	
Low-level inpu current	ıt	l _{IL}	_	—	-0.5	-	-5.0	μΑ	$V_I = GND, V_G$	_{CC} = 5.5V	
Maximum	\overline{Q}_1 to	lo		—	1.0		10.0	μA	$V_{I}=V_{T+}\text{,}$	$V_{\text{O}} = V_{\text{CC}}$	
output leak current	\overline{Q}_{32}		-	—	-1.0	9	-10.0		V_{T-} $V_{CC} = 5.5V$	$V_{\text{O}} = GND$	
Quiescent stat dissipation cur	te rrent	I _{CC}	_		40.0	5	400.0	μΑ	$V_{I} = V_{CC}, \ GN$ $V_{CC} = 5.5V$	D,	

Note: 1. All typical values are at $V_{CC} = 5 \text{ V}$, Ta = 25°C

2. Ta = -40 to +70°C

Switching Characteristics

									$(V_{CC} = 5V)$
					Limits				
					Ta = –	40 to			
				Ta = 25°C	+85	°C			
Item		Symbol	Min	Тур	Max	Min	Max	Unit	Conditions
Maximum clock frequen	f _{max}	5	30	—	4	_	MHz	$C_{\text{L}}=50 \text{ pF}$	
Output enable time to	$CK-\overline{Q}_1$ to \overline{Q}_{32}	t _{PZL}	—	35	150	—	200	ns	$R_L = 1 \ k\Omega$
low-level	(Turned on)								(Note 2)
Output disable time	$CK-\overline{Q}_1$ to \overline{Q}_{32}	t _{PLZ}	—	35	200	—	250	ns	
from low-level	(Turned off)								
Low-to-high, high-to-	CK-SQ ₃₂	t _{PLH}	—	35	100	—	130	ns	
low output		t _{PHL}	—	40	100	—	130	ns	
propagation time									
Output enable time to	S_D-Q_1 to Q_{32}	t _{PZL}	—	35	150	—	200	ns	
low-level	(Turned on)								
Low-to-high output	S _D -SQ ₃₂	t _{PLH}	_	40	100	—	130	ns	
propagation time									
Output enable time to	LE- Q_1 to Q_{32}	t _{PZL}		30	100		130	ns	
low-level	(Turned on)								
Output disable time	LE- Q_1 to Q_{32}	t _{PLZ}		35	150	P.	200	ns	
from low-level	(Turned off)								
Output enable time to	OE-Q ₁ to Q ₃₂	t _{PZL}		30	100	·	130	ns	
low-level	(Turned on)								
Output disable time $\overline{OE} - \overline{Q}_1$ to \overline{Q}		t _{PLZ}		35 🤇	150	—	200	ns	
from low-level	(Turned off)			0					
Input capacitance		Cı	_	3	10	—	10	pF	
Output capacitance		Co		6	15	—	15	pF	OE-V _{CC}
Power dissipation capac	citance (Note 1)	CPD		160	—	—	—	pF	

Note 1. C_{PD} is the equivalent capacitance of IC calculated by the operating power dissipation without load. The operating power dissipation without load is given as follows.

 $P_{D} = C_{PD} \bullet V_{CC}^{2} \bullet f_{I} + I_{CC} \bullet V_{CC}$

Timing Requirements

$(V_{CC} = 5V)$

			Ta = 25°C		to +85°C			
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Conditions
CK, \overline{LE} , \overline{S}_D pulse width	tw	100	16	—	130		ns	(Note 2)
Setup time A to CK	t _{su}	100	27	—	130		ns	
Hold time A to CK	t _h	10	5	—	15		ns	
Hold time LE to CK		50	15	—	70			
Recovery time CK to \overline{S}_D	t _{rec}	50	20	_	70	_	ns	

Note: 2. Test Circuit



(1) Characteristics of pulse generator (PG): tr = 6 ns, tf = 6 ns

(2) C_L includes probe and stray capacitance.

Timing Chart



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Package Dimensions



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